

## REMARKS

Claims 6-12 are pending in the present application. Claim 6 is in independent form. Claims 8 and 12 are hereby amended. No new matter was introduced as a result of the amendments. Entry of the amendments and favorable reconsideration is respectfully requested.

The Office Action indicated that the use of the term "claim" in the specification was improper. Applicant believes this informality was corrected by way of the preliminary amendment filed October 12, 2006.

The Office Action rejected claim 8 under 35 U.S.C. §112 as being indefinite for the use of the phrase "low cost." Appropriate correction has been made.

The Office Action rejected claim 12 under 35 U.S.C. §112 as being indefinite for the use of the number "150." Appropriate correction has been made.

Claim 6 was rejected under 35 U.S.C. §102(b) as being unpatentable over *Hirose* (US Patent 6,407,345). The method of *Hirose* is based on a copper-clad printed board substrate 30A into which corresponding borings are drilled for the throughplating whereby the electric throughplating is effected with the assistance of a specific method alone [sic] within said borings (column 15, step (1), lines 8 and 9 ("... electroless plating 33 is deposited within the passing hole ...").

In contrast, the method of claim 6 carries out the throughplating in that an "electrically conductive general layer is built up." This, however, represents a completely different course of action. This new course of action teaches the non-necessity of a copper-clad printed board substrate at the time of drilling the passing holes for the throughplatings. Accordingly, the copper-cladding is carried out at the same time as the production of the electric throughplating. Since the throughplating does not only occur in the through-holes alone but an electrically conductive general layer, namely the copper-cladding, is deposited, whereby the throughplating occurs at the same time in the through-holes. [... sic]

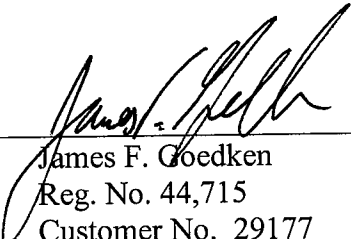
In addition, *Hirose* does not provide any information to the effect that the electric throughplating is not limited to the through-holes but is effected in connection with the depositing of an electrically conductive general layer which eliminates the necessity of already having a copper-clad printed board substrate.

For at least these reasons, Applicant submits the rejection of claim 6 is improper and should be withdrawn. Claims 7-12 depend directly or indirectly from claim 6 and are allowable for at least the same reasons. Applicants respectfully submit that the patent application is in condition for allowance and request a Notice of Allowance be issued. The Commissioner is authorized to charge and credit Deposit Account No. 02-1818 for any additional fees associated with the submission of this Response. Please reference docket number 112740-1145.

Respectfully submitted,

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Dated: January 31, 2008